

In the Specification:

In the prior office action response filed November 11, 2002, Applicants amended the paragraph beginning on page 15, line 11. In the amendment herein, the paragraph beginning on page 15, line 11 is further amended as follows:

As illustrated for the embodiments of FIGS. 2 and 3, the multiple redistribution structure on either the top surface **48** or the bottom surface **49** of the substrate **10** has N dielectric layers (denoted as dielectric layers 1, 2, ..., N), N metal planes (denoted as metal planes 1, 2, ..., N), and a microvia structure, wherein $N \geq 2$. Dielectric layer 1 (i.e., redistribution layer **60** or **80**) is on the top surface **48** or the bottom surface **49** of the substrate **10** and thus also on a metallic plane; i.e., on the metal plane **51** or the metal plane **52**, respectively. Thus, the metal planes **51** and **52** are each called a “metallic plane” for purposes of the notation being discussed herein. Metal plane 1 (i.e., metal plane **140** or **141**) is on dielectric layer 1, dielectric layer 2 (i.e., redistribution layer **70** or **90**) is on dielectric layer 1 and metal plane 1, metal plane 2 (i.e., metal plane **150** or **151**) is on dielectric layer 2, ..., dielectric layer N is on dielectric layer N-1 and metal plane N-1, and metal plane N is on dielectric layer N. The microvia structure electrically couples the metal plane N to the metallic plane (i.e., the metal plane **51** or the metal plane **52**) by a collection of microvias coupled with intervening metal planes. The microvia structure includes a microvia or a portion of a microvia through each of the N dielectric layers. Many such combinations of microvias are possible. An example microvia combination is N microvias (i.e., a microvia in each dielectric layer) such that microvia J is electrically coupled to microvia J-1 by metal plane J-1 for J=2, 3, ..., N. To illustrate, FIG. 3 has N=3 and shows: microvia **345** electrically coupled to microvia **385** by metal plane **380** (specifically, conductive pad **386** in metal plane **380**), microvia **385**

electrically coupled to microvia 334 by metal plane 340 (specifically, conductive pad 338 in metal plane 340), and microvia 334 electrically coupled to metal plane 51 by conductive pad 33, which electrically couples the metal plane 395 to the metal plane 51 in light of the fact that conductive pad 346 of metal plane 395 is integral with, and thus electrically connected with, the conductive plating of the microvia 346. Another microvia combination includes a microvia that passes through two or more dielectric layers (e.g., the microvia 144 of FIG. 2). For example and although not shown explicitly in FIG. 3, a microvia could pass through redistribution layers 360, 370, and 390[[, or]]. In FIG. 3, microvia 383 passes through redistribution layers 370 and 390, just as microvia 144 of FIG. 2 passes through redistribution layers 60 and 70. Thus in FIG. 3, [[a]] microvia 383 passing through redistribution layers 370 and 390 could be electrically coupled by metal plane 340 to a microvia (e.g., the microvia 332, 333, or 334) in redistribution layer 360.